- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

The '51 and 'S51 contain two independent 2-wide 2-input AND-OR-INVERT gates. They perform the Boolean function $Y = \overline{AB + CD}$.

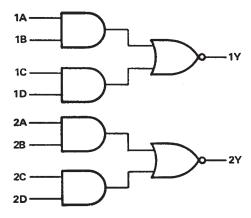
The 'LS51 contains one 2-wide 3-input and one 2-wide 2-input AND-OR-INVERT gates. They perform the Boolean functions $1Y = \overline{(1A \cdot 1B \cdot 1C) + (1D \cdot 1E \cdot 1F)}$ and $2Y = \overline{(2A \cdot 2B) + (2C \cdot 2D)}$.

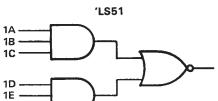
The SN5451, SN54LS51, and SN54S51 are characterized for operation over the full military temperature range of -55 °C to 125 °C. The SN7451, SN74LS51 and SN74S51 are characterized for operation from 0 °C to 70 °C.

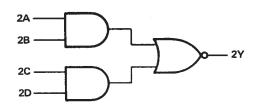
logic diagrams

1E









PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



SN5451...J PACKAGE SN54551...J OR W PACKAGE SN7451...N PACKAGE SN74551...D OR N PACKAGE (TOP VIEW) 1A 1 14 VCC 2A 2 13 1B 2B 3 12 NU

SN5451, SN54LS51, SN54S51 SN7451, SN74LS51, SN74S51 AND-OR-INVERT GATES

SDLS113 - DECEMBER 1983 - REVISED MARCH 1988

	3	μ^{2}	NO
2C 🗌	4	11	NU
2D 🗌	5	10	1D
2Y 🗖	6	90	1C
	7	8	1Y

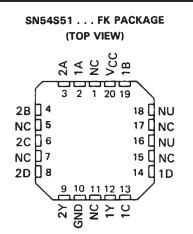
SN54	51	• •	. W P/	٩C	KAGE
	(1	го	P VIEW)	
NU	d	1	U 14	þ	1D
NU	d	2	13	þ	1C
1A		3	12	þ	1Y
Vcc		4	11	þ	GND
1B		5	10	þ	2Y
2A		6	9	Ь	2D
2B		7	8	þ	2C

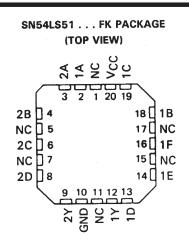
SN54LS51 ... J OR W PACKAGE SN74LS51 ... D OR N PACKAGE (TOP VIEW)

NC- No internal connection NU - Make no external connection

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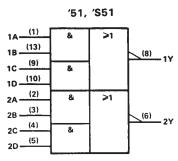
SN5451, SN54LS51, SN54S51 SN7451, SN74LS51, SN74S51 AND-OR-INVERT GATES SDLS113 – DECEMBER 1983 – REVISED MARCH 1988



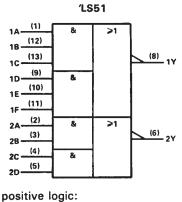


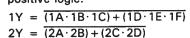
NC - No internal connection NU - Make no external connection

logic symbols[†]



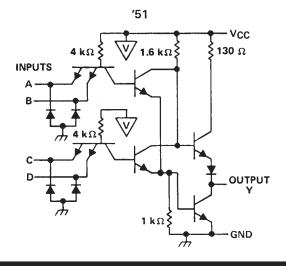
positive logic: $Y = \overline{AB + CD}$



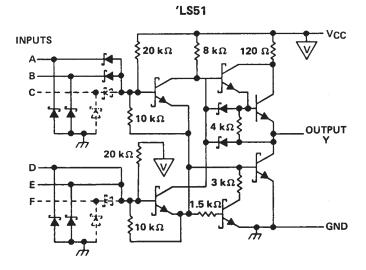


[†]These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

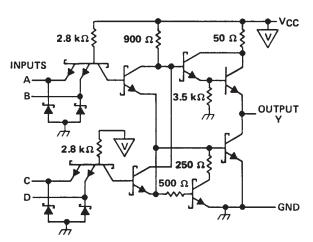
schematics







′S51



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (See Note 1): '51, 'LS51, 'S51 7 V
Input voltage: '51, 'S51 5.5 V
′LS51
Operating free-air temperature range: SN54'
SN74′
Storage temperature range – 65 °C to 150 °C

NOTE 1: Voltage values are with respect to network ground terminal.



SN5451, SN54LS51, SN54S51 SN7451, SN74LS51, SN74S51 AND-OR-INVERT GATES

SDLS113 - DECEMBER 1983 - REVISED MARCH 1988

recommended operating conditions

		SN5451						
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
юн	High-level output current			- 0.4			- 0.4	mA
IOL	Low-level output current			16			16	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		SN5451	SN7451	UNIT
PARAMETER	TEST CONDITIONS †	MIN TYP‡ MA	X MIN TYP‡ MAX	
VIK	$V_{CC} = MIN, I_{I} = -12 \text{ mA}$	- 1.	5 - 1.5	V
Voн	$V_{CC} = MIN, V_{IL} = 0.8 V, I_{OH} = -0.4 mA$	2.4 3.4	2.4 3.4	V
VOL	$V_{CC} = MIN$, $V_{IH} = 2V$, $I_{OL} = 16 \text{ mA}$	0.2 0.	4 0.2 0.4	V
1	$V_{CC} = MAX, V_1 = 5.5 V$		1 1	mA
ιн	V _{CC} = MAX, V ₁ = 2.4 V	4	0 40	μA
μL	$V_{CC} = MAX, V_1 = 0.4 V$	- 1.	6 – 1.6	mA
IOS§	V _{CC} = MAX	- 20 - 5	5 - 18 - 55	mA
ICCH	V _{CC} = MAX, V ₁ = 0 V	4	8 4 8	mA
ICCL	V _{CC} = MAX, See Note 2	7.4 1	4 7.4 14	mA

t For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$. § Not more than one output should be shorted at a time.

NOTE 2: All inputs of one AND gate at 4.5 V, all others at GND.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		түр	MAX	UNIT
tplh tphl	Any	Y	R _L = 400 Ω, C _L = 15 pF		13 8	22 15	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



recommended operating conditions

		S	SN54LS51			SN74LS51			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5,5	4.75	5	5.25	V	
VIH	High-level input voltage	2			2			V	
VIL	Low-level input voltage			0.7			0.8	V	
юн	High-level output current			- 0.4			- 0.4	mA	
IOL	Low-level output current			4			8	mA	
TA	Operating free-air temperature	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEAT AONID		s	N54LS	51	S	UNIT		
PARAMETER		TEST CONDITIONS †			TYP ‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN,	l _l = – 18 mA				- 1.5			- 1.5	• V
V _{OH}	$V_{CC} = MIN,$	$V_{IL} = MAX,$	I _{OH} = - 0.4 mA	2.5	3.4		2.7	3.4		V
V	$V_{CC} = MIN,$	V _{IH} = 2 V,	IOL = 4 mA		0.25	0.4		0.25	0.4	v
VOL	$V_{CC} = MIN,$	V _{IH} = 2 V,	IOL = 8 mA					0.35	0.5	
lj –	V _{CC} = MAX,	V _I = 7 V				0.1			0.1	mA
Чн	$V_{CC} = MAX,$	V _I = 2.7 V				20			20	μA
կլ	V _{CC} = MAX,	V = 0.4 V				- 0.4			- 0.4	mA
IOS§	V _{CC} = MAX			- 20		- 100	- 20		- 100	mA
Іссн	V _{CC} = MAX,	V ₁ = 0 V			0.8	1.6		8.0	1.6	mA
ICCL	V _{CC} = MAX,	See Note 2			1,4	2.8		1.4	2.8	mA

t For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 \ddagger All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

NOTE 2: All inputs of one AND gate at 4.5 V, all others at GND.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	MIN TYP	МАХ	UNIT	
tPLH	A	×		0 15 - 5	12	20	n\$
^t PHL	Any	Y Y	$R_{L} = 2 k\Omega,$	C _L = 15 pF	12.5	20	រាន

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



SN5451, SN54LS51, SN54S51 SN7451, SN74LS51, SN74S51 AND-OR-INVERT GATES

SDLS113 - DECEMBER 1983 - REVISED MARCH 1988

recommended operating conditions

			SN54S51			SN74S51			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage	2			2			V	
VIL	Low-level input voltage			0.8			0.8	V	
ЮН	High-level output current			1			- 1	mA	
IOL	Low-level output current			20			20	mA	
TA	Operating free-air temperature	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

					SN54S51			SN74S51			
PARAMETER	TEST CONDITIONS †		MIN	TYP‡	MAX	MIN	TYP‡	MAX			
VIK	$V_{CC} = MIN,$	l _l = 18 mA			- 1.2					V	
VOH	V _{CC} = MIN,	V _{IL} = 0.8 V,	I _{OH} = - 1 mA	2.5	3.4		2.7	3.4		V	
VOL	$V_{CC} = MIN,$	V _{IH} = 2 V,	IOL = 20 mA			0.5			0.5	V	
i į	$V_{CC} = MAX,$	V1 = 5.5 V				1			1	mA	
Чн	V _{CC} = MAX,	V _I = 2.7 V				50			50	μA	
η _L	V _{CC} = MAX,	V1 = 0.5 V				- 2			- 2	mA	
IOS§	V _{CC} = MAX			- 40		- 100	- 40		100	mA	
Іссн	V _{CC} = MAX,	V = 0 V			8.2	17.8		8.2	17.8	mA	
ICCL	V _{CC} = MAX,	See Note 2			13.6	22		13.6	22	mA	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$.

§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second. NOTE 2: All inputs of one AND gate at 4.5 V, all others at GND.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	DITIONS	MIN TYP	МАХ	UNIT
t _{PLH}			5 000 0	0 - 15 - 5	3.5	5.5	ns
^t PHL			R _L = 280 Ω,	С _L = 15 pF	3,5	5.5	ns
^t PLH	Any	Y	R _L = 280 Ω,	CL = 50 pF	5		ns
^t PHL			n_ = 200 <i>st</i> ,	Γ200 <i>μ</i> , σ30 μ 5.5		ns	

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/00502BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00502BCA	Samples
JM38510/07401BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07401BCA	Samples
JM38510/07401BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07401BDA	Samples
JM38510/30401BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30401BCA	Samples
M38510/00502BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00502BCA	Samples
M38510/07401BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07401BCA	Samples
M38510/07401BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07401BDA	Samples
M38510/30401BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30401BCA	Samples
SN5451J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN5451J	Samples
SN54LS51J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS51J	Samples
SN54S51J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S51J	Samples
SN74LS51D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS51	Samples
SN74LS51DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS51	Samples
SN74LS51N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS51N	Samples
SN74LS51NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS51	Samples
SN74S51D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	S51	Samples
SN74S51N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S51N	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ5451J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ5451J	Samples
SNJ5451W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ5451W	Samples
SNJ54LS51J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS51J	Samples
SNJ54LS51W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS51W	Samples
SNJ54S51FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S 51FK	Samples
SNJ54S51J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S51J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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OTHER QUALIFIED VERSIONS OF SN54LS51, SN54S51, SN74LS51, SN74S51 :

- Catalog : SN74LS51, SN74S51
- Military : SN54LS51, SN54S51

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



Texas

STRUMENTS

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*A	I dimensions are nominal												
	Device	-	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
Γ	SN74LS51DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
	SN74LS51NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



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PACKAGE MATERIALS INFORMATION

9-Aug-2022



*All dimensions are nominal

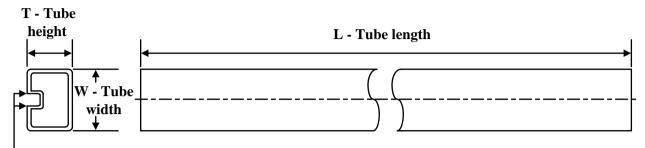
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS51DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74LS51NSR	SO	NS	14	2000	356.0	356.0	35.0

TEXAS INSTRUMENTS

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TUBE



- B - Alignment groove width

*All dimensions are nominal								
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
JM38510/07401BDA	W	CFP	14	1	506.98	26.16	6220	NA
M38510/07401BDA	W	CFP	14	1	506.98	26.16	6220	NA
SN74LS51D	D	SOIC	14	50	506.6	8	3940	4.32
SN74LS51N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS51N	N	PDIP	14	25	506	13.97	11230	4.32
SN74S51D	D	SOIC	14	50	506.6	8	3940	4.32
SN74S51N	N	PDIP	14	25	506	13.97	11230	4.32
SN74S51N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ5451W	W	CFP	14	1	506.98	26.16	6220	NA
SNJ54LS51W	W	CFP	14	1	506.98	26.16	6220	NA
SNJ54S51FK	FK	LCCC	20	1	506.98	12.06	2030	NA

LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14



GENERIC PACKAGE VIEW

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



J0014A

EXAMPLE BOARD LAYOUT

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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